

FIG. 1A

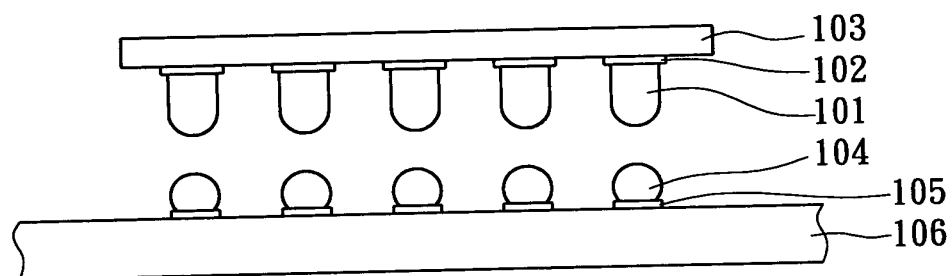


FIG. 1A
(PRIOR ART)

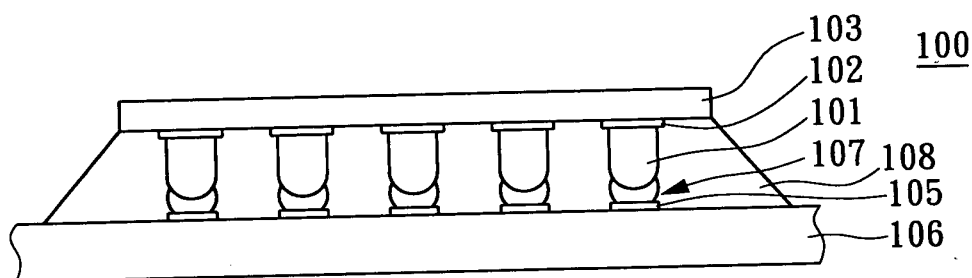


FIG. 1B
(PRIOR ART)

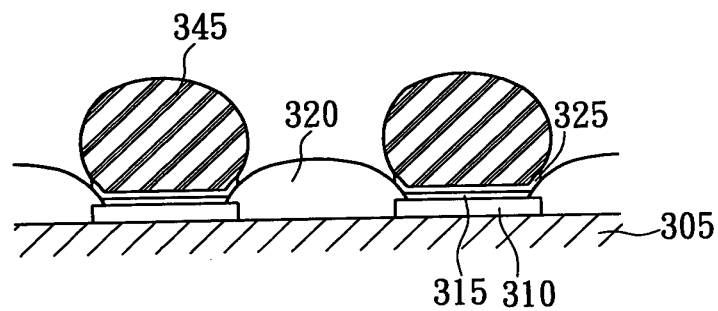


FIG. 3E

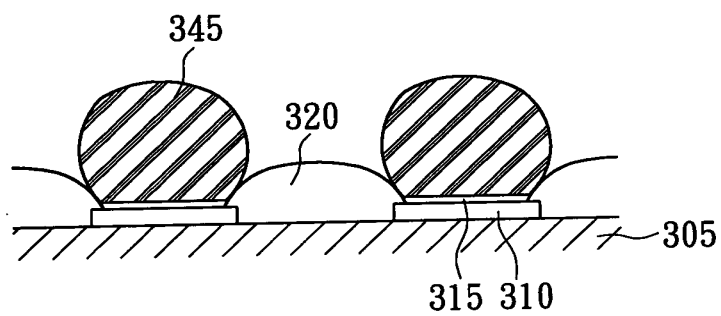


FIG. 3F

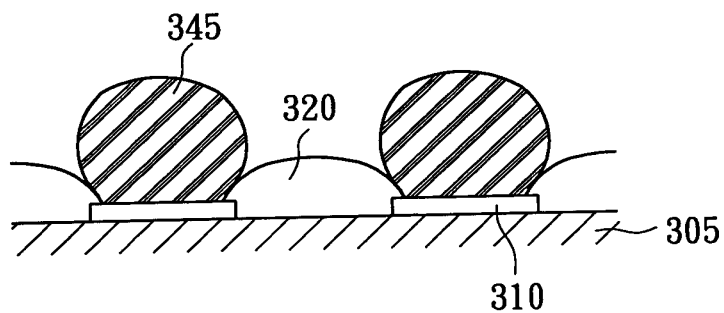


FIG. 3G

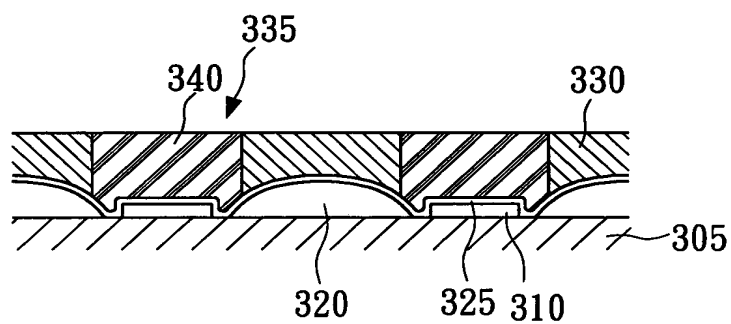


FIG. 4A

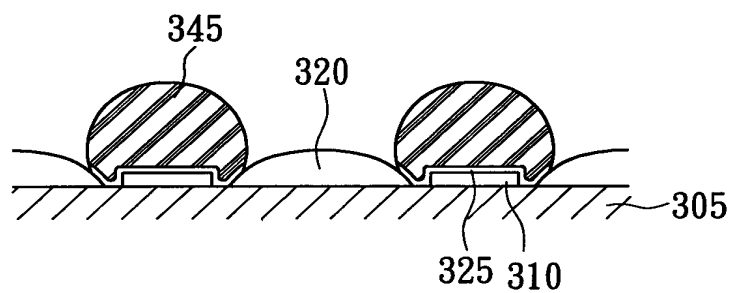


FIG. 4B

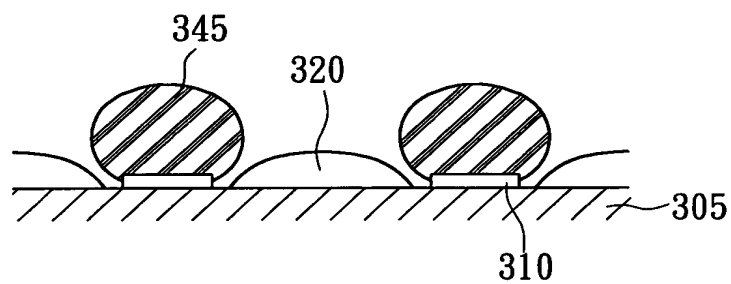


FIG. 4C

FIG. 4A

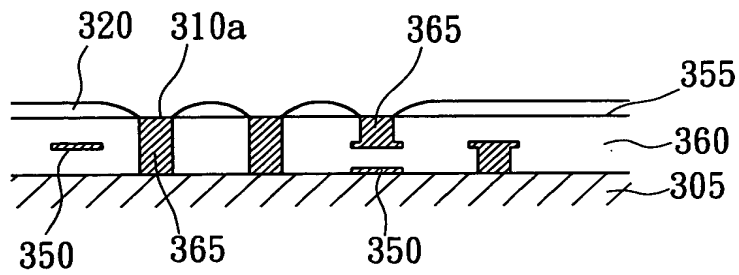


FIG. 5A

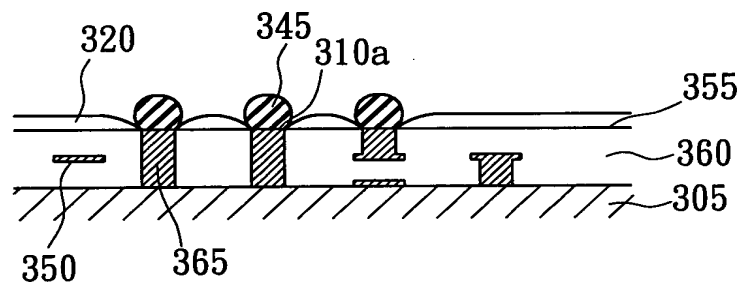


FIG. 5B

This diagram shows a cross-sectional view of a device. A substrate 305 is at the bottom. Two solder balls 310 are mounted on the substrate. A layer 320 is formed on top of the solder balls. Two circular features 345 are formed on the layer 320. A top layer 370 is shown above the solder balls, with a gap 375 between the solder balls.

A cross-sectional view of a device. Two circular components, labeled 320, are positioned on a substrate 305. Each component 320 is sandwiched between two horizontal layers, 310 (bottom) and 370 (top). A gap, labeled 380, is formed between the two components 320. The top layer 370 has a top surface 375. The substrate 305 is shown with hatching below it.

FIG. 6B

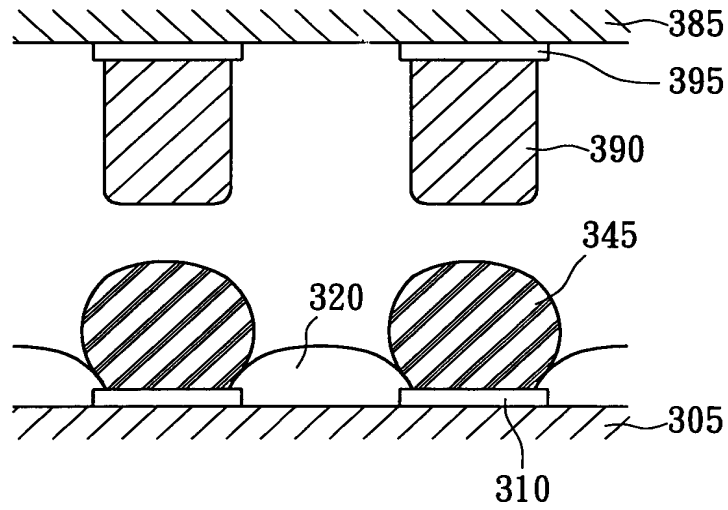


FIG. 7A

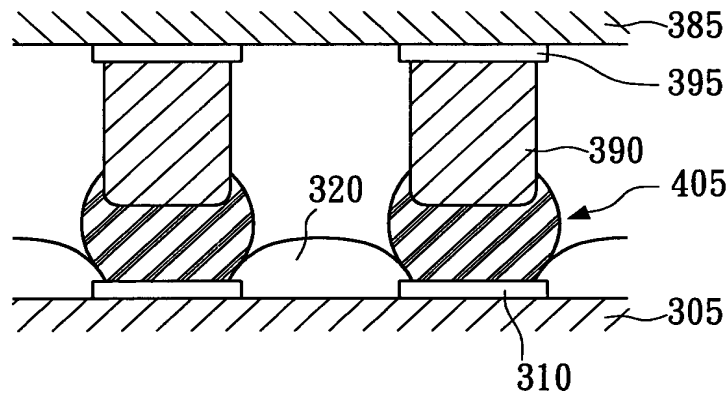


FIG. 7B

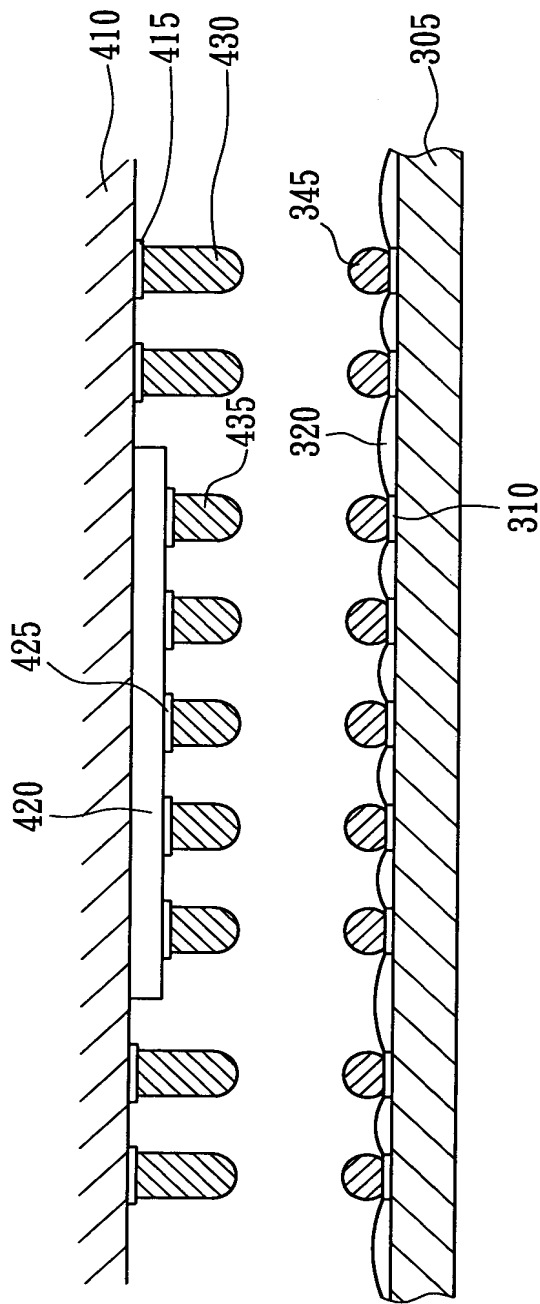


FIG. 8A

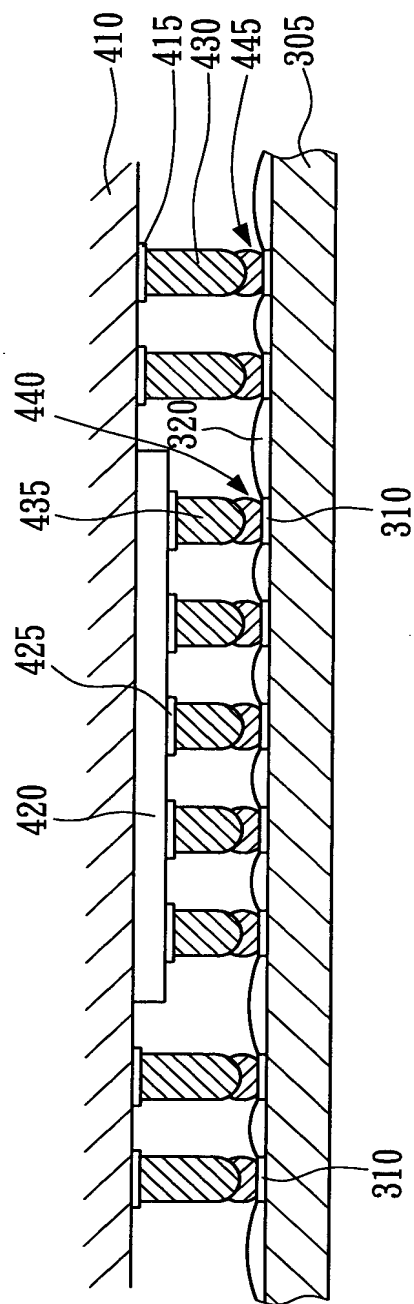


FIG. 8B

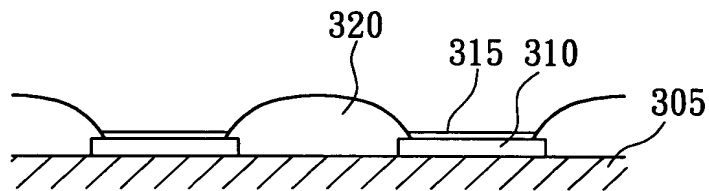


FIG. 3A

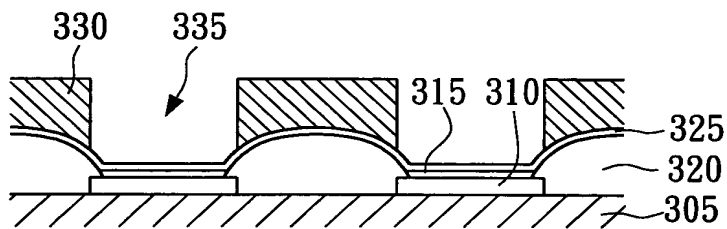


FIG. 3B

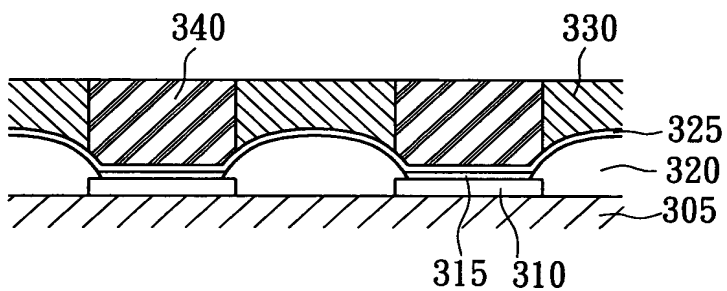


FIG. 3C

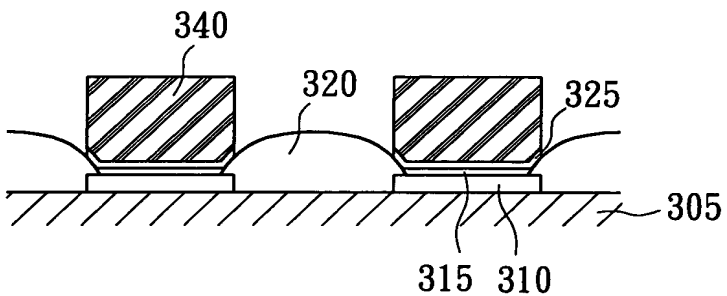


FIG. 3D